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September 2006

FDP8860

N-Channel PowerTrench® MOSFET

30V, **80A**, **2.5m**Ω

Features

- Max $r_{DS(on)}$ = 2.5m Ω at V_{GS} = 10V, I_D = 80A
- Max $r_{DS(on)}$ = 2.9m Ω at V_{GS} = 4.5V, I_D = 80A
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIL Capability (Single Pulse and Repetitive Pulse)
- RoHS Compliant

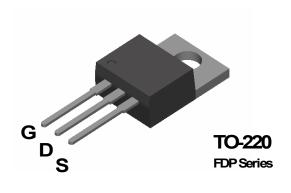


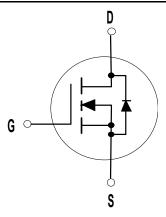
General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(on)}$ and fast switching speed.

Application

- DC DC Conversion
- Start / Alternator Sytems





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DS}	Drain to Source Voltage		30	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current -Continuous (Package limited)	T _C = 25°C	80	
I_D	-Continuous (Silicon limited)	T _C = 25°C	219	Α
	-Pulsed	(Note 1)	556	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	673	mJ
P_{D}	Power Dissipation		254	W
T _J , T _{STG}	Operating and Storage Temperature		-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case TO220	0.59	°C/W	Ī
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO220	62	C/VV	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8860	FDP8860	TO220AB	Tube	N/A	50 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Characteristics						
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 1mA$, $V_{GS} = 0V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 1mA, referenced to 25°C		22		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24V,$ $V_{GS} = 0V$ $T_{J} = 150^{\circ}C$			1 250	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1	1.6	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C		-9.6		mV/°C
	I Irain to Source (in Registance	V _{GS} = 10V, I _D = 80A		1.9	2.5	mΩ
r		$V_{GS} = 5V, I_{D} = 80A$		2.0	2.8	
r _{DS(on)}		$V_{GS} = 4.5V, I_D = 80A$		2.1	2.9	11152
		$V_{GS} = 10V$, $I_D = 80A$, $T_J = 150$ °C		2.9	3.8	
g _{FS}	Forward Transconductance	$V_{DS} = 10V, I_{D} = 80A$		3.4		S

Dynamic Characteristics

C _{iss}	Input Capacitance	\\ -45\\\\\ -0\\	9200	12240	pF
C _{oss}	Output Capacitance	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	1700	2260	pF
C _{rss}	Reverse Transfer Capacitance	T - TIVILIZ	1060	1590	pF
R_q	Gate Resistance	f = 1MHz	1.7		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	., ,=,,,	35	56	ns
t _r	Rise Time	V_{DD} = 15V, I_{D} = 80A V_{GS} = 5V, R_{GEN} = 3 Ω	135	216	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} - 5V, K _{GEN} - 322	64	103	ns
t _f	Fall Time		59	95	ns
$Q_{g(TOT)}$	Total Gate Charge at 10V	V _{GS} = 0V to 10V	158	222	nC
Q _{g(5)}	Total Gate Charge at 5V	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 15V$ $I_{D} = 80A$	81	114	nC
Q_{gs}	Gate to Source Gate Charge	I _D = 80A	27		nC
Q_{gd}	Gate to Drain "Miller" Charge		33		nC

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Forward Voltage	Source to Drain Diode, Fenward Voltage	V _{GS} = 0V, I _S = 80A	= 0V, I _S = 80A 0.88	0.88	1.25	\/
	$V_{GS} = 0V, I_{S} = 40A$		0.81	1.2	V	
t _{rr}	Reverse Recovery Time	$I_{\rm F}$ = 80A, di/dt = 100A/µs		60	90	ns
Q _{rr}	Reverse Recovery Charge	1F - 80A, αναί - 100ΑνμS		74	111	nC

Notes:
1: Pulse Test: Pulse Width < 80μs, Duty cycle < 0.5%.
2: Starting T_J =25°C, L= 0.3mH, I_{AS} = 67A,V_{DD} = 27V, V_{GS} = 10V.

Typical Characteristics T_J = 25°C unless otherwise noted

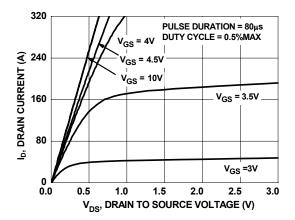


Figure 1. On Region Characteristics

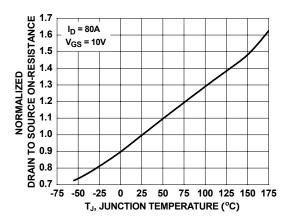


Figure 3. Normalized On Resistance vs Junction Temperature

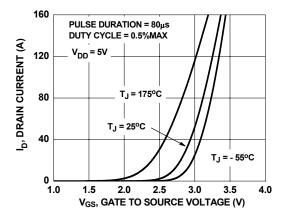


Figure 5. Transfer Characteristics

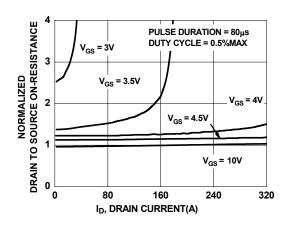


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

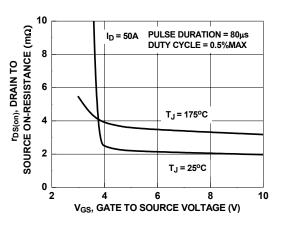


Figure 4. On-Resistance vs Gate to Source Voltage

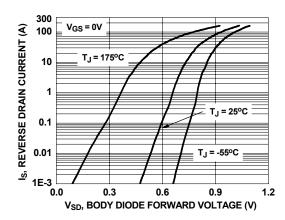


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

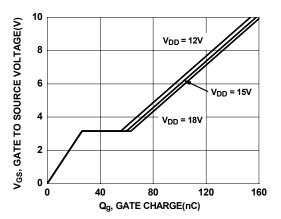


Figure 7. Gate Charge Characteristics

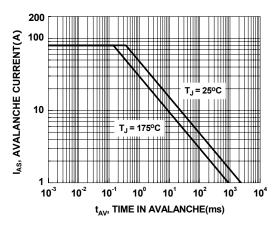


Figure 9. Unclamped Inductive Switching Capability

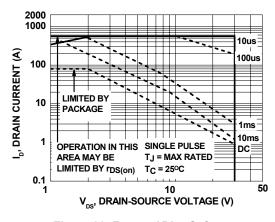


Figure 11. Forward Bias Safe Operating Area

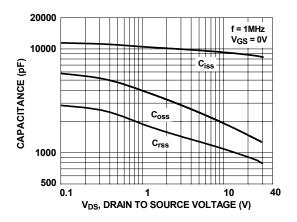


Figure 8. Capacitance vs Drain to Source Voltage

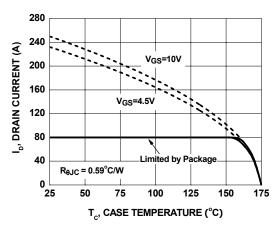


Figure 10. Maximum Continuous Drain Current vs Case Temperature

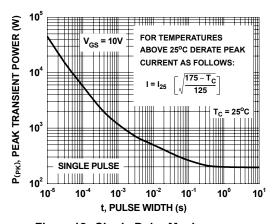


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

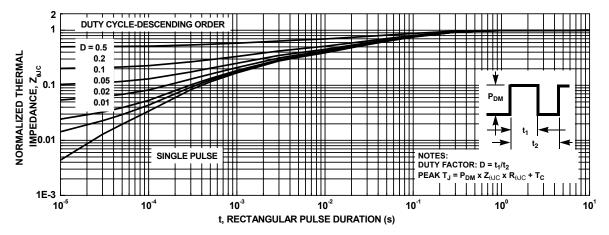


Figure 13. Transient Thermal Response Curve

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